NOA T 3 5008

Sheet 1

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)

Complete if Known **Application Number** 10/816,179 Filing Date March 31, 2004 First Named Inventor Chung J. Lee Art Unit 1763 **Examiner Name** Rudy Zervigon Attorney Docket Number **DSI302** 

Examiner Initials*	Cite No.1	Document Number  Number-Kind Code <sup>2 (# known)</sup>	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
	1	<sup>US-</sup> 6,362,091	03-26-2002	Andideh et al.	,
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		FORE	IGN PATENT DOCU	MENTS				
Examiner Initials*	Cite No.1	Foreign Patent Document	Publication Date	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear			۲۰
		Country Code <sup>3</sup> "Number <sup>4</sup> "Kind Code <sup>8</sup> (# known)	MM-DD-YYYY	7,				
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